

Description

The FKBA3031 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -30VI_{D} = -70A$

 $R_{DS(ON)}$ < $8.8 \text{m}\Omega$ V_{GS} =-10V

Application

Battery protection

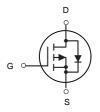
Load switch

Uninterruptible power supply

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) | |
|------------|-----------|------------|----------|--|
| FKBA3031 | DFN5X6-8L | HXY MOSFET | 5000 | |

DFN5X6-8L



P-Channel MOSFET

Absolute Maximum Ratings (Tc=25 ℃ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|-------|
| VDS | Drain-Source Voltage | -30 | V |
| Vgs | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | -70 | А |
| I _D @T _C =75°C | Continuous Drain Current, V _{GS} @ 10V ¹ | -40 | Α |
| Ірм | Pulsed Drain Current ² | -175 | Α |
| EAS | Single Pulse Avalanche Energy ³ | 31 | mJ |
| P _D @T _C =25°C | Total Power Dissipation⁴ | 31.2 | W |
| Тѕтс | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |
| Rыс | Thermal Resistance Junction-Case ¹ | 4 | °C/W |
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | 61 | °C/W |



ElectricalCharacteristics(T J=25°C unless otherwise noted)

| Parameter | | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|--|--------------------------------|---------------------|--|------|------|------|------|--|
| Static Characteristics | | | | | | | | |
| Drain-Source Breakdown V | Drain-Source Breakdown Voltage | | $V_{GS} = 0V, I_{D} = -250\mu A$ | -30 | - | - | V | |
| Gate-body Leakage current | | I _{GSS} | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA | |
| Zero Gate Voltage Drain Current | T _J =25°C | I _{DSS} | V _{DS} = -24V, V _{GS} = 0V | - | - | -1 | μА | |
| | T _J =55°C | | | - | - | -5 | | |
| Gate-Threshold Voltage | Gate-Threshold Voltage | | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | -1.0 | -1.6 | -2.5 | V | |
| Drain-Source On-Resistance ² | | _ | V _{GS} = -10V, I _D = -12A | - | 6 | 8.8 | | |
| | | R _{DS(on)} | V _{GS} = -4.5V, I _D = -8A | - | 9 | 14 | mΩ | |
| Forward Transconductance | Forward Transconductance | | V _{DS} = -5V, I _D = -20A | - | 28 | - | S | |
| Dynamic Characteristic | es | 1 | , | 1 | • | | | |
| Input Capacitance | | C _{iss} | | - | 4320 | - | | |
| Output Capacitance Reverse Transfer Capacitance | | Coss | V _{DS} = -15V, V _{GS} =0V, f =1MHz | - | 529 | - | pF | |
| | | Crss | | - | 487 | - | | |
| Switching Characterist | Switching Characteristics | | | | | | | |
| Gate Resistance | | Rg | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | - | 4.0 | - | Ω | |
| Total Gate Charge | Total Gate Charge | | | - | 45 | - | nC | |
| Gate-Source Charge | | Q _{gs} | $V_{GS} = -10V, V_{DS} = -15V,$ $I_{D} = -15A$ | - | 8.5 | - | | |
| Gate-Drain Charge | | Q _{gd} | | - | 12.8 | - | | |
| Turn-On Delay Time | | t _{d(on)} | | - | 18.9 | - | | |
| Rise Time | | tr | $V_{GS} = -10V, V_{DD} = -15V,$ | - | 15.7 | - | nS | |
| Turn-Off Delay Time | | t _{d(off)} | $R_G = 2.5\Omega$, $I_D = -15A$ | - | 64.8 | - | | |
| Fall Time | | t _f | | - | 36.5 | - | | |
| Drain-Source Body Dio | de Charac | teristics | | ı | 1 | ı | I | |
| Diode Forward Voltage ² | | V _{SD} | I _S = -1A, V _{GS} = 0V | - | - | -1 | V | |
| Continuous Source Current ^{1,5} | | Is | V _G =V _D =0V , Force Current | - | - | -70 | Α | |

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD} = -25V, V_{GS} = -10V, L= 0.1mH, I_{AS} = -25A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Electrical And Thermal Characteristics (Curves)

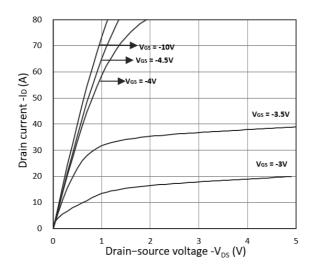


Figure 1. Output Characteristics

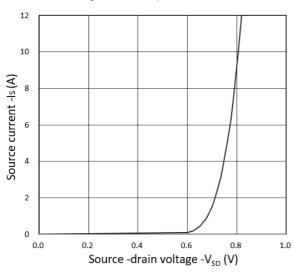


Figure 3. Forward Characteristics of Reverse

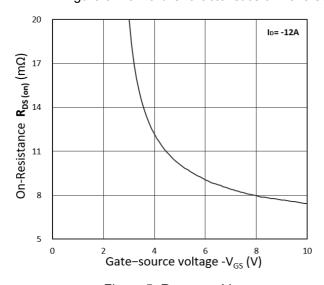


Figure 5. $R_{DS(on)}$ vs. V_{GS}

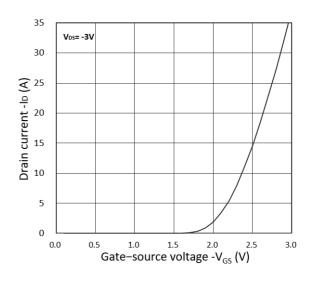


Figure 2. Transfer Characteristics

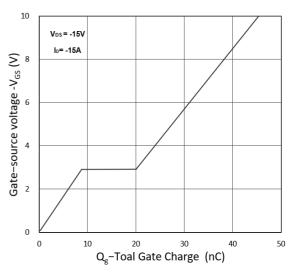


Figure 4. Gate Charge Characteristics

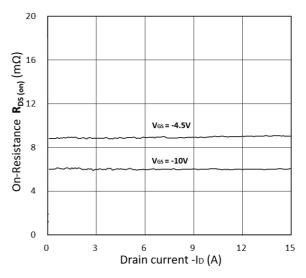


Figure 6. $R_{DS(on)}$ vs. I_D



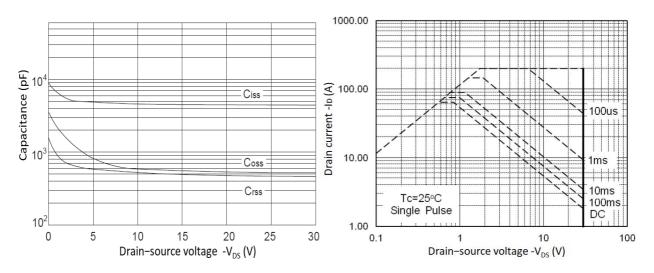


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

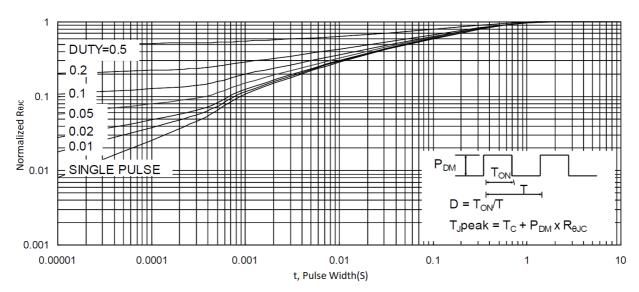


Figure 9. Normalized Maximum Transient Thermal Impedance

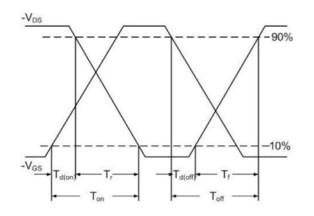


Figure 10. Switching Time Waveform

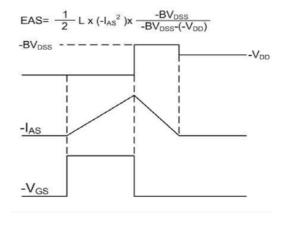


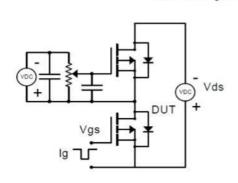
Figure 11. Unclamped Inductive Switching

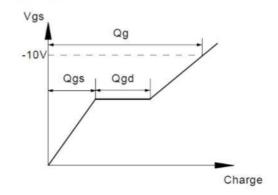
Waveform



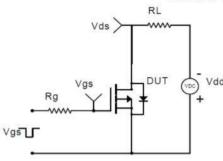
Test Circuit

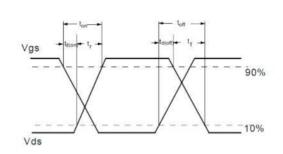
Gate Charge Test Circuit & Waveform



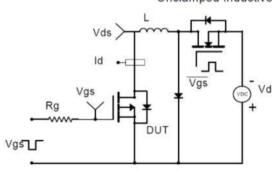


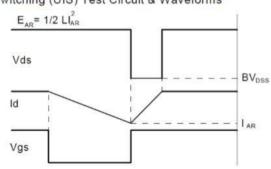
Resistive Switching Test Circuit & Waveforms



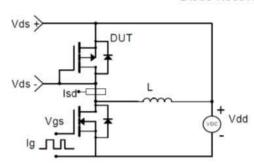


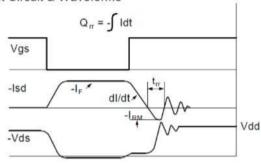
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





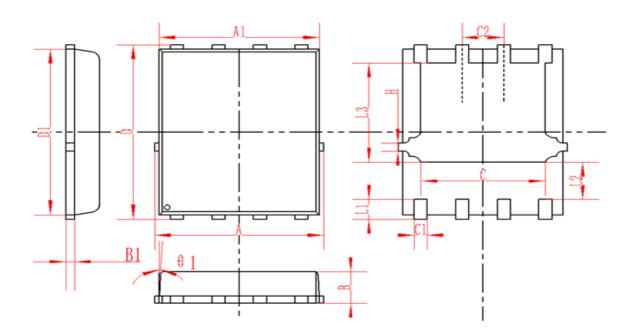
Diode Recovery Test Circuit & Waveforms







DFN5X6-8L Package Information



| SYMBOL | MM | | | INCH | | |
|--------|----------|------|----------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 4.95 | 5 | 5.05 | 0.195 | 0.197 | 0.199 |
| A1 | 4.82 | 4.9 | 4.98 | 0.190 | 0.193 | 0.196 |
| D | 5.98 | 6 | 6.02 | 0.235 | 0.236 | 0.237 |
| D1 | 5.67 | 5.75 | 5.83 | 0.223 | 0.226 | 0.230 |
| В | 0.9 | 0.95 | 1 | 0.035 | 0.037 | 0.039 |
| B1 | 0.254REF | | 0.010REF | | | |
| С | 3.95 | 4 | 4.05 | 0.156 | 0.157 | 0.159 |
| C1 | 0.35 | 0.4 | 0.45 | 0.014 | 0.016 | 0.018 |
| C2 | 1.27TYP | | | 0.5TYP | | |
| θ1 | 8° | 10° | 12° | 8° | 10° | 12° |
| L1 | 0.63 | 0.64 | 0.65 | 0.025 | 0.025 | 0.026 |
| L2 | 1.2 | 1.3 | 1.4 | 0.047 | 0.051 | 0.055 |
| L3 | 3.415 | 3.42 | 3.425 | 0.134 | 0.135 | 0.135 |
| Н | 0.24 | 0.25 | 0.26 | 0.009 | 0.010 | 0.010 |



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